# FUĴĨTSU

## **PRODUCT CHANGE NOTIFICATION**

PCN No:	PCN-SM2110
Announcement date	2021-05-28

1. Affected Product(s):

SOP8 MB85RC16PNF-G-JNERE1, MB85RC16PNF-G-JNE1 MB85RC64PNF-G-JNERE1, MB85RC64PNF-G-JNE1

2. Description of Change

The mold resin of SOP8 will be changed from A maker to B maker.

3. Reason of Phasing Out:

Tongfu Microelectronics, one of our backend manufacturing subcontractors, gave us a short notice that the mold resin currently used will be unavailable, resulting in the stop of the production as soon as their current stock is used up. After several rounds of urgent negotiation with the subcontractor, we have decided to reluctantly change the mold resin in order to keep the supply of our products to our valued customers.

#### 4. Substitute

#### **Products after changing**

- MB85RC16PNF-G-JNERE1, MB85RC16PNF-G-JNE1 Changed products are scheduled to be shipped out from July.
- MB85RC64PNF-G-JNERE1, MB85RC64PNF-G-JNE1 Changed products are scheduled to be shipped out from the end of August (After reliability evaluation).

Without any feedback by due date, we will deem to agree to that changing mold resin.



Contact details for	any further information:
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### Originator:

FUJITSU Semiconductor Memry
Solution Limited.
Quality Assurance Dept.
ŶAMĂZAKI
Shin-Yokohama TECH Building
3-9-18 Shin-Yokohama, Kohoku-
Ku,Yokohama, Kanagawa,
222-0033, Japan
+81-45-473-9067
hiro.yamazaki@fujitsu.com
FUJITSU Semiconductor Memory
Solution Limited.
Marketing Dept.
Director KAWAKUBO
+81-45-755-7035
t.kawakubo@fujitsu.com
FUJITSU Semiconductor Memory
Solution Limited.
Quality Assurance Dept.
Director INOUE
+81-45-473-9067
ken-ichi.inoue@jp.fujitsu.com